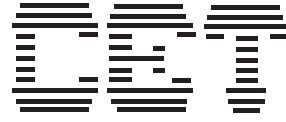


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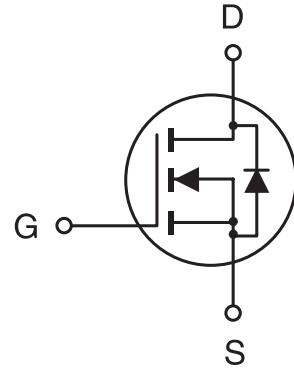
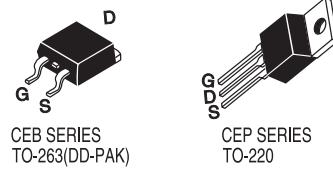
PRELIMINARY

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## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 60V , 60A ,  $R_{DS(ON)}=25m\Omega$  @  $V_{GS}=10V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handling capability.
- TO-220 & TO-263 package.



### ABSOLUTE MAXIMUM RATINGS (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous -Pulsed	I <sub>D</sub>	60	A
	I <sub>DM</sub>	144	A
Drain-Source Diode Forward Current	I <sub>S</sub>	60	A
Maximum Power Dissipation @ T <sub>c</sub> =25°C Derate above 25°C	P <sub>D</sub>	100	W
		0.7	W/ °C
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to 175	°C

### THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	2	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62.5	°C/W

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## ELECTRICAL CHARACTERISTICS (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>DRAIN-SOURCE AVALANCHE RATING<sup>a</sup></b>						
Single Pulse Drain-Source Avalanche Energy	E <sub>AS</sub>	V <sub>DD</sub> =25V, I <sub>D</sub> =100A		200		mJ
Maximum Drain-Source Avalanche Current	I <sub>AS</sub>	L=25μH		100		A
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V			25	μA
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
<b>ON CHARACTERISTICS<sup>a</sup></b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2	2.8	4	V
Drain-Source On-State Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =24A		19	25	mΩ
On-State Drain Current	I <sub>D(ON)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =10V	60			A
Forward Transconductance	g <sub>F</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =24A		20		S
<b>SWITCHING CHARACTERISTICS<sup>b</sup></b>						
Turn-On Delay Time	t <sub>D(ON)</sub>	V <sub>DD</sub> =30V, I <sub>D</sub> =48A, V <sub>GS</sub> =10V, R <sub>GS</sub> =7.5Ω		15	20	ns
Rise Time	t <sub>r</sub>			250	300	ns
Turn-Off Delay Time	t <sub>D(OFF)</sub>			45	60	ns
Fall Time	t <sub>f</sub>			130	150	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =48V, I <sub>D</sub> =48A, V <sub>GS</sub> =10V		64	70	nC
Gate-Source Charge	Q <sub>gs</sub>			8		nC
Gate-Drain Charge	Q <sub>gd</sub>			13		nC

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## ELECTRICAL CHARACTERISTICS ( $T_c=25^\circ\text{C}$ unless otherwise noted)

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Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>DYNAMIC CHARACTERISTICS<sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS}=25\text{V}, V_{GS}=0\text{V}$ $f=1.0\text{MHz}$		1178	1600	pF
Output Capacitance	$C_{oss}$			428	560	pF
Reverse Transfer Capacitance	$C_{rss}$			95	130	pF
<b>DRAIN-SOURCE DIODE CHARACTERISTICS<sup>b</sup></b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0\text{V}, I_S=24\text{A}$		0.9	1.3	V

### Notes

- a.Pulse Test:Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- b.Guaranteed by design, not subject to production testing.

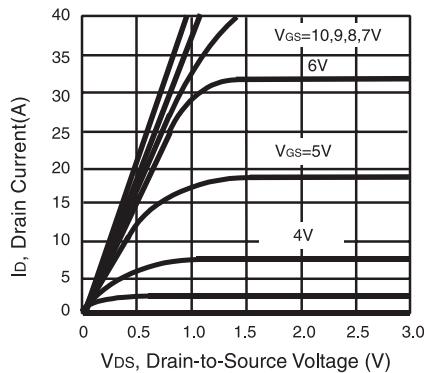


Figure 1. Output Characteristics

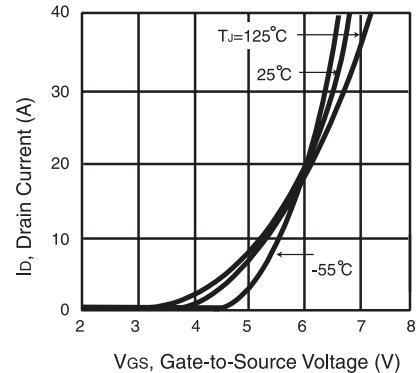
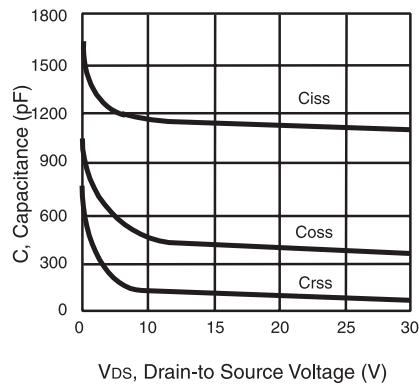


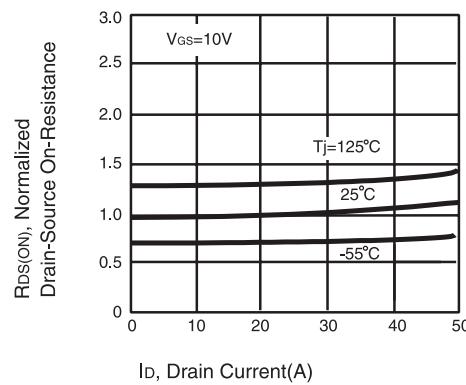
Figure 2. Transfer Characteristics

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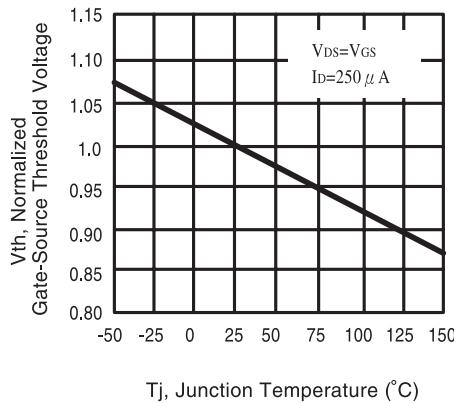
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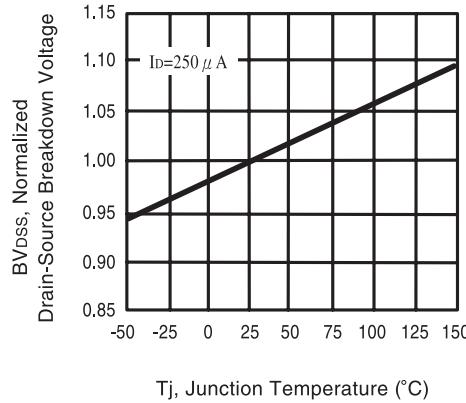
**Figure 3. Capacitance**



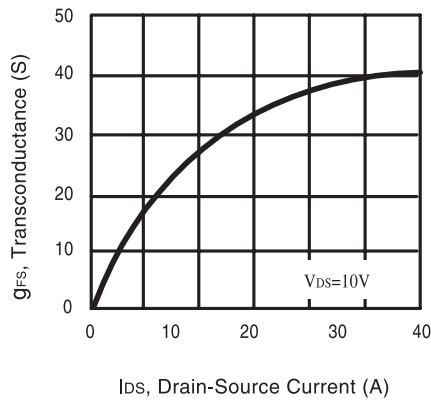
**Figure 4. On-Resistance Variation with Drain Current and Temperature**



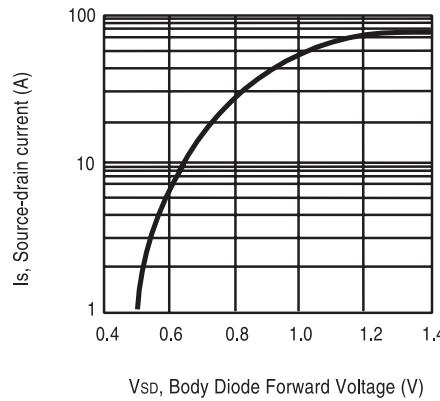
**Figure 5. Gate Threshold Variation with Temperature**



**Figure 6. Breakdown Voltage Variation with Temperature**



**Figure 7. Transconductance Variation with Drain Current**



**Figure 8. Body Diode Forward Voltage Variation with Source Current**

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